

Title (en)
PHOTOSTRUCTURED PASTE

Title (de)
PHOTOSTRUKTURIERE PASTE

Title (fr)
PATE PHOTOSTRUCTURABLE

Publication
EP 1296913 A2 20030402 (DE)

Application
EP 01921161 A 20010308

Priority
• DE 0100867 W 20010308
• DE 10015502 A 20000314

Abstract (en)
[origin: DE10015502A1] Photostructurizable paste, especially for the production of structurized resistance films or wiring traces on green ceramic substrates, contains a filler and light-sensitive organic binder, having a polymer, photoinitiator, thermal polymerization inhibitor, organic disulfide and organic solvent. The filler is a platinum (Pt) powder or its compound or its mixture with a ceramic powder or ceramic precursor compound.
[origin: DE10015502A1] Photostructurizable paste, especially for the production of structurized resistance films or wiring traces on green ceramic substrates, contains a filler and light-sensitive organic binder, having a polymer, photoinitiator, thermal polymerization inhibitor, organic disulfide and organic solvent. The filler is a platinum (Pt) powder or its compound or its mixture with a ceramic powder or ceramic precursor compound.

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C07C 1/00

IPC 8 full level
C04B 41/51 (2006.01); **C04B 41/88** (2006.01); **C09D 5/25** (2006.01); **G01K 7/18** (2006.01); **G03F 7/004** (2006.01); **G03F 7/031** (2006.01); **G03F 7/038** (2006.01); **H01B 1/22** (2006.01); **H01C 17/065** (2006.01); **H05K 1/09** (2006.01); **H05K 1/16** (2006.01); **H05K 3/02** (2006.01)

CPC (source: EP KR US)
C04B 41/009 (2013.01 - EP US); **C04B 41/5122** (2013.01 - EP US); **C04B 41/88** (2013.01 - EP US); **G01K 7/18** (2013.01 - EP US); **G03F 7/0047** (2013.01 - EP US); **G03F 7/028** (2013.01 - KR); **H01C 17/0654** (2013.01 - EP US); **H01C 17/06553** (2013.01 - EP US); **C04B 2111/00844** (2013.01 - EP US); **H05K 1/092** (2013.01 - EP US); **H05K 1/167** (2013.01 - EP US); **H05K 3/02** (2013.01 - EP US)

Citation (search report)
See references of WO 0168567A2

Designated contracting state (EPC)
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